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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	224 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f627t-04e-ss

1.0 PIC16F62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16F62X Product Identification System section (Page 167) at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

1.1 FLASH Devices

FLASH devices can be erased and reprogrammed electrically. This allows the same device to be used for prototype development, pilot programs and production.

A further advantage of the electrically-erasable FLASH is that it can be erased and reprogrammed in-circuit, or by device programmers, such as Microchip's PICSTART® Plus, or PRO MATE® II programmers.

1.2 Quick-Turnaround Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who chose not to program a medium-to-high quantity of units and whose code patterns have stabilized. The devices are standard FLASH devices but with all program locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

1.3 Serialized Quick-Turnaround Production (SQTP^{sm}) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

RETLW **Return with Literal in W**

Syntax: [*label*] RETLW k

Operands: $0 \le k \le 255$

Operation: $k \rightarrow (W)$;
$TOS \rightarrow PC$

Status Affected: None

Encoding:

11	01xx	kkkk	kkkk

Description: The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
CALL TABLE;W contains table
          ;offset value
•         ;W now has table
value
•
•
ADDWF PC  ;W = offset
RETLW k1  ;Begin table
RETLW k2  ;
•
•
•
RETLW kn  ; End of table
```

TABLE

Before Instruction
W = 0x07
After Instruction
W = value of k8

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN

Operands: None

Operation: $TOS \rightarrow PC$

Status Affected: None

Encoding:

00	0000	0000	1000

Description: Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
RETURN
```

After Interrupt
PC = TOS

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

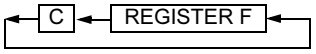
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example

```
RLF     REG1, 0
```

Before Instruction
REG1 = 1110 0110
C = 0
After Instruction
REG1 = 1110 0110
W = 1100 1100
C = 1

16.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI C compilers for Microchip's PIC17CXXX and PIC18CXXX family of microcontrollers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

16.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian manages the creation and modification of library files of pre-compiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

16.5 MPLAB C30 C Compiler

The MPLAB C30 C compiler is a full-featured, ANSI compliant, optimizing compiler that translates standard ANSI C programs into dsPIC30F assembly language source. The compiler also supports many command-line options and language extensions to take full advantage of the dsPIC30F device hardware capabilities, and afford fine control of the compiler code generator.

MPLAB C30 is distributed with a complete ANSI C standard library. All library functions have been validated and conform to the ANSI C library standard. The library includes functions for string manipulation, dynamic memory allocation, data conversion, time-keeping, and math functions (trigonometric, exponential and hyperbolic). The compiler provides symbolic information for high level source debugging with the MPLAB IDE.

16.6 MPLAB ASM30 Assembler, Linker, and Librarian

MPLAB ASM30 assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 compiler uses the assembler to produce it's object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

16.7 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC hosted environment by simulating the PICmicro series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user defined key press, to any pin. The execution can be performed in Single-Step, Execute Until Break, or Trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and MPLAB C18 C Compilers, as well as the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent, economical software development tool.

16.8 MPLAB SIM30 Software Simulator

The MPLAB SIM30 software simulator allows code development in a PC hosted environment by simulating the dsPIC30F series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user defined key press, to any of the pins.

The MPLAB SIM30 simulator fully supports symbolic debugging using the MPLAB C30 C Compiler and MPLAB ASM30 assembler. The simulator runs in either a Command Line mode for automated tasks, or from MPLAB IDE. This high speed simulator is designed to debug, analyze and optimize time intensive DSP routines.

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16.14 PICDEM 1 PICmicro Demonstration Board

The PICDEM 1 demonstration board demonstrates the capabilities of the PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The sample microcontrollers provided with the PICDEM 1 demonstration board can be programmed with a PRO MATE II device programmer, or a PICSTART Plus development programmer. The PICDEM 1 demonstration board can be connected to the MPLAB ICE in-circuit emulator for testing. A prototype area extends the circuitry for additional application components. Features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs.

16.15 PICDEM.net Internet/Ethernet Demonstration Board

The PICDEM.net demonstration board is an Internet/ Ethernet demonstration board using the PIC18F452 microcontroller and TCP/IP firmware. The board supports any 40-pin DIP device that conforms to the standard pinout used by the PIC16F877 or PIC18C452. This kit features a user friendly TCP/IP stack, web server with HTML, a 24L256 Serial EEPROM for Xmodem download to web pages into Serial EEPROM, ICSP/MPLAB ICD 2 interface connector, an Ethernet interface, RS-232 interface, and a 16 x 2 LCD display. Also included is the book and CD-ROM *"TCP/IP Lean, Web Servers for Embedded Systems,"* by Jeremy Bentham

16.16 PICDEM 2 Plus Demonstration Board

The PICDEM 2 Plus demonstration board supports many 18-, 28-, and 40-pin microcontrollers, including PIC16F87X and PIC18FXX2 devices. All the necessary hardware and software is included to run the demonstration programs. The sample microcontrollers provided with the PICDEM 2 demonstration board can be programmed with a PRO MATE II device programmer, PICSTART Plus development programmer, or MPLAB ICD 2 with a Universal Programmer Adapter. The MPLAB ICD 2 and MPLAB ICE in-circuit emulators may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area extends the circuitry for additional application components. Some of the features include an RS-232 interface, a 2 x 16 LCD display, a piezo speaker, an on-board temperature sensor, four LEDs, and sample PIC18F452 and PIC16F877 FLASH microcontrollers.

16.17 PICDEM 3 PIC16C92X Demonstration Board

The PICDEM 3 demonstration board supports the PIC16C923 and PIC16C924 in the PLCC package. All the necessary hardware and software is included to run the demonstration programs.

16.18 PICDEM 17 Demonstration Board

The PICDEM 17 demonstration board is an evaluation board that demonstrates the capabilities of several Microchip microcontrollers, including PIC17C752, PIC17C756A, PIC17C762 and PIC17C766. A programmed sample is included. The PRO MATE II device programmer, or the PICSTART Plus development programmer, can be used to reprogram the device for user tailored application development. The PICDEM 17 demonstration board supports program download and execution from external on-board FLASH memory. A generous prototype area is available for user hardware expansion.

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17.2 DC Characteristics: PIC16F62X (Commercial, Industrial, Extended) PIC16LF62X (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended Operating voltage VDD range as described in DC spec Table 17-1 and Table 17-2				
Param. No.	**Sym**	**Characteristic/Device**	**Min**	**Typ†**	**Max**	**Unit**	**Conditions**
	VIL	**Input Low Voltage**					
		I/O ports					
D030		with TTL buffer	VSS	—	0.8	V	VDD = 4.5V to 5.5V
					0.15 VDD	V	otherwise
D031		with Schmitt Trigger input	VSS		0.2 VDD	V	
D032		MCLR, RA4/T0CKI,OSC1 (in ER mode)	VSS	—	0.2 VDD	V	**(Note1)**
D033		OSC1 (in XT and HS)	VSS	—	0.3 VDD	V	
		OSC1 (in LP)	VSS	—	0.6 VDD - 1.0	V	
	VIH	**Input High Voltage**					
		I/O ports					
D040		with TTL buffer	2.0V	—	VDD	V	VDD = 4.5V to 5.5V
			.25 VDD + 0.8V		VDD	V	otherwise
D041		with Schmitt Trigger input	0.8 VDD	—	VDD	V	
D042		MCLR RA4/T0CKI	0.8 VDD	—	VDD	V	
D043		OSC1 (XT, HS and LP)	0.7 VDD	—	VDD	V	
D043A		OSC1 (in ER mode)	0.9 VDD			V	**(Note1)**
D070	IPURB	**PORTB weak pull-up current**	50	200	400	µA	VDD = 5.0V, VPIN = VSS
	IIL	**Input Leakage Current(2), (3)**					
		I/O ports (Except PORTA)			±1.0	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D060		PORTA	—	—	±0.5	µA	VSS ≤ VPIN ≤ VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	µA	VSS ≤ VPIN ≤ VDD
D063		OSC1, MCLR	—	—	±5.0	µA	VSS ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	VOL	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	IOL=8.5 mA, VDD=4.5V, -40° to +85°C
			—	—	0.6	V	IOL=7.0 mA, VDD=4.5V, +125°C
D083		OSC2/CLKOUT (ER only)	—	—	0.6	V	IOL=1.6 mA, VDD=4.5V, -40° to +85°C
			—	—	0.6	V	IOL=1.2 mA, VDD=4.5V, +125°C
	VOH	**Output High Voltage(3)**					
D090		I/O ports (Except RA4)	VDD - 0.7	—	—	V	IOH=-3.0 mA, VDD=4.5V, -40° to +85°C
			VDD - 0.7	—	—	V	IOH=-2.5 mA, VDD=4.5V, +125°C
D092		OSC2/CLKOUT (ER only)	VDD - 0.7	—	—	V	IOH=-1.3 mA, VDD=4.5V, -40° to +85°C
			VDD - 0.7	—	—	V	IOH=-1.0 mA, VDD=4.5V, +125°C
D150	VOD	**Open-Drain High Voltage**		—	8.5	V	RA4 pin PIC16F62X, PIC16LF62X*
		Capacitive Loading Specs on Output Pins					
D100*	COSC2	OSC2 pin		—	15	pF	In XT, HS and LP modes when external clock used to drive OSC1.
D101*	Cio	All I/O pins/OSC2 (in ER mode)		—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In ER oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC16F62X be driven with external clock in ER mode.

2: The leakage current on the MCLR pin is strongly dependent on applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

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TABLE 17-1: COMPARATOR SPECIFICATIONS

	Operating Conditions: 3.0V < VDD <5.5V, -40°C < TA < +125°C, unless otherwise stated.						
Param No.	**Characteristics**	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D300	Input offset voltage	VIOFF	—	±5.0	±10	mV	
D301*	Input Common mode voltage	VICM	0	—	VDD - 1.5	V	
D302*	Common Mode Rejection Ratio	CMRR	55	—	—	db	
300* 300A	Response Time(1)	TRESP	—	150	400 600	ns ns	16F62X 16LF62X
301	Comparator Mode Change to Output Valid*	TMC2OV	—	—	10	µs	

* These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (VDD - 1.5)/2 while the other input transitions from VSS to VDD.

TABLE 17-2: VOLTAGE REFERENCE SPECIFICATIONS

	Operating Conditions: 3.0V < VDD < 5.5V, -40°C < TA < +125°C, unless otherwise stated.						
Spec No.	**Characteristics**	**Sym**	**Min**	**Typ**	**Max**	**Units**	**Comments**
D310	Resolution	VRES	VDD/24	—	VDD/32	LSb	
D311	Absolute Accuracy	VRaa	— —	— —	1/4 1/2	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)
D312*	Unit Resistor Value (R)	VRur	—	2k	—	Ω	
310*	Settling Time(1)	Tset	—	—	10	µs	

* These parameters are characterized but not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from `0000` to `1111`.

TABLE 17-4: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency(1)	DC	—	4	MHz	XT and ER Osc mode, VDD = 5.0V
			DC	—	20	MHz	HS Osc mode
			DC	—	200	kHz	LP Osc mode
		Oscillator Frequency(1)		—	4	MHz	ER Osc mode, VDD = 5.0V
			0.1	—	4	MHz	XT Osc mode
			1	—	20	MHz	HS Osc mode
				—	200	kHz	LP Osc mode
			3.65	4	4.28	MHz	INTRC mode (fast), VDD = 5.0V
				37		kHz	INTRC mode (slow)
4	INTRC	Internal Calibrated RC	3.65	4.00	4.28	MHz	VDD = 5.0V
5	ER	External Biased ER Frequency	10 kHz		8 MHz		VDD = 5.0V
1	Tosc	External CLKIN Period(1)	250	—	—	ns	XT and ER Osc mode
			50	—	—	ns	HS Osc mode
			5	—	—	µs	LP Osc mode
		Oscillator Period(1)	250	—	—	ns	ER Osc mode
			250	—	10,000	ns	XT Osc mode
			50	—	1,000	ns	HS Osc mode
			5			µs	LP Osc mode
				250		ns	INTRC mode (fast)
				27		µs	INTRC mode (slow)
2	Tcy	Instruction Cycle Time	1.0	TCY	DC	ns	TCY = 4/FOSC
3	TosL, TosH	External CLKIN (OSC1) High External CLKIN Low	100 *	—	—	ns	XT oscillator, TOSC L/H duty cycle*

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-based period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max" cycle time limit is "DC" (no clock) for all devices.

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NOTES:

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Note: The graphs and tables provided in this section are for design guidance and are not tested.

FIGURE 18-2: MAXIMUM I_{DD} VS F_{OSC} OVER V_{DD} (HS MODE)

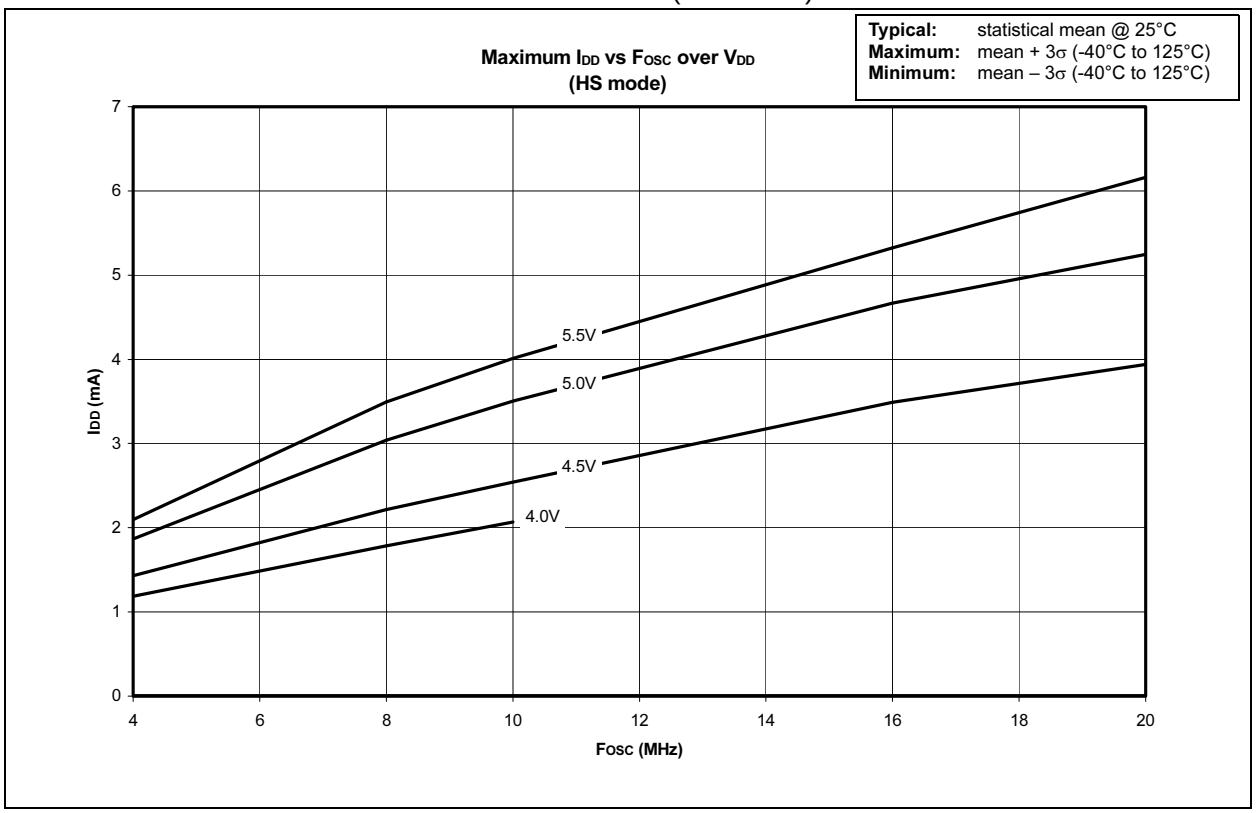
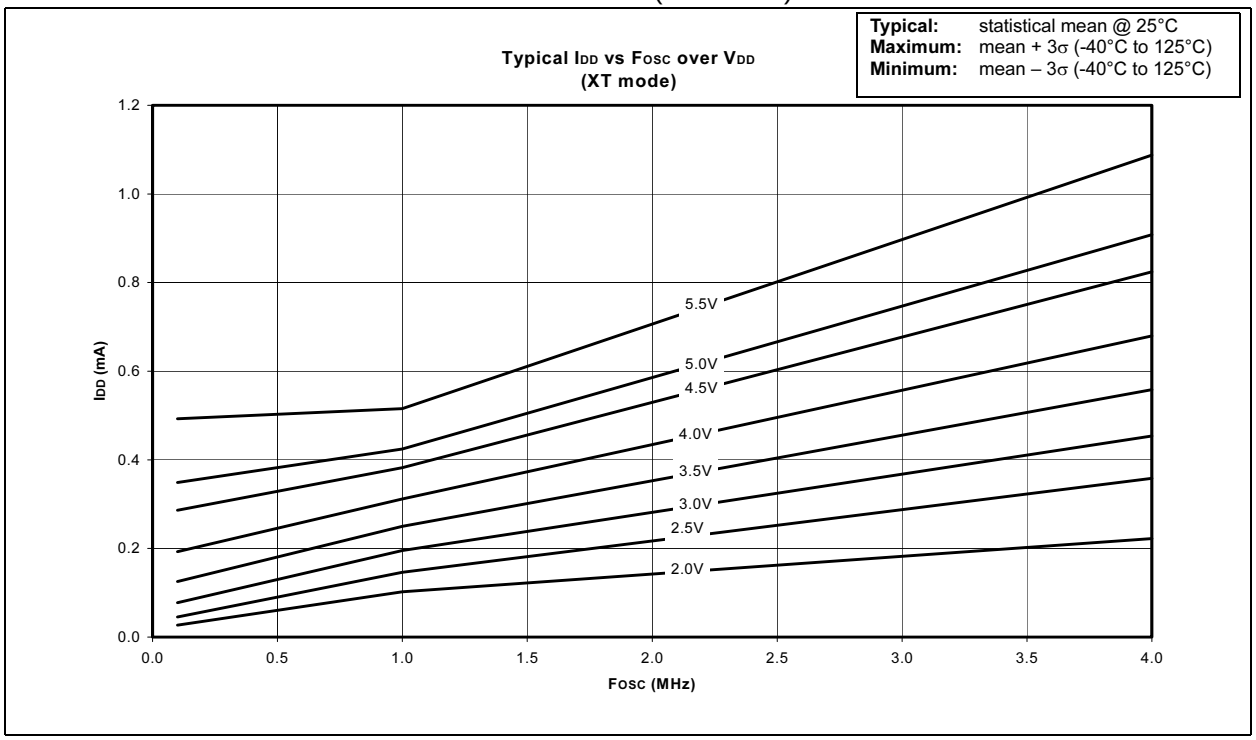


FIGURE 18-3: TYPICAL I_{DD} VS F_{OSC} OVER V_{DD} (XT MODE)



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Note: The graphs and tables provided in this section are for design guidance and are not tested.

FIGURE 18-22: VIN VS VDD TTL

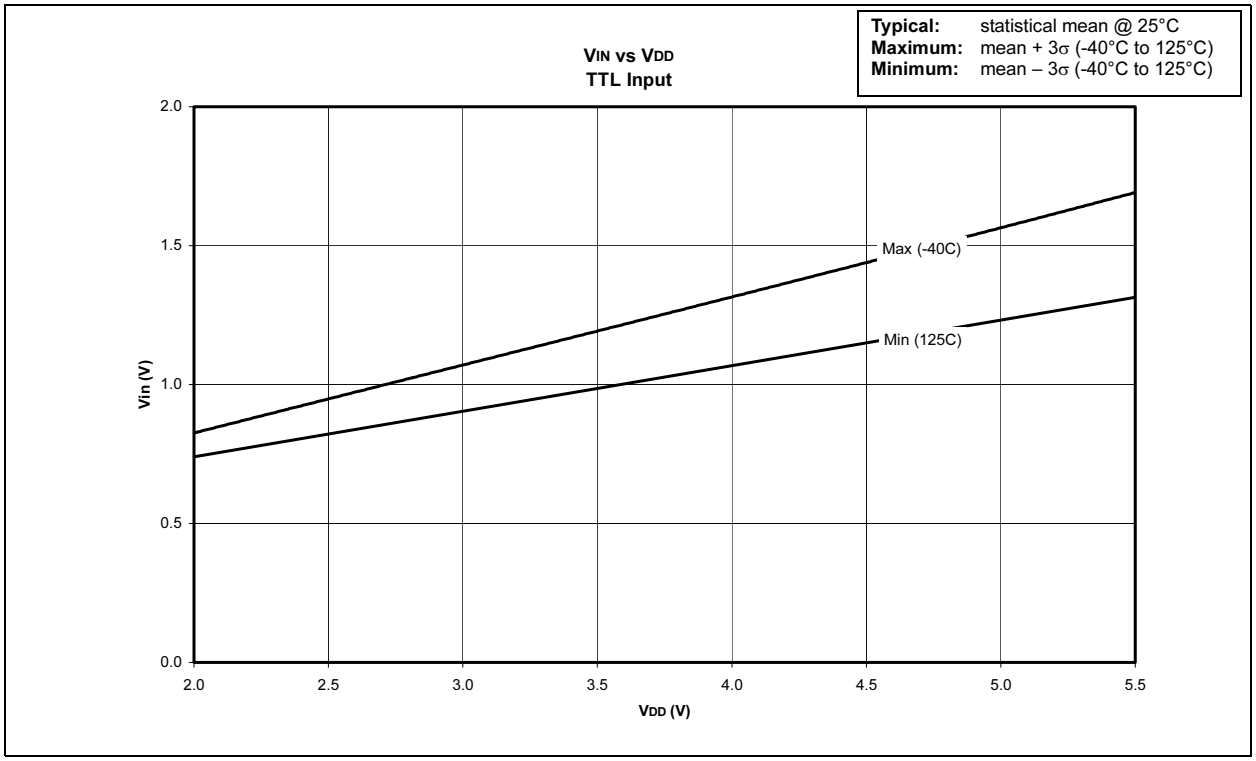
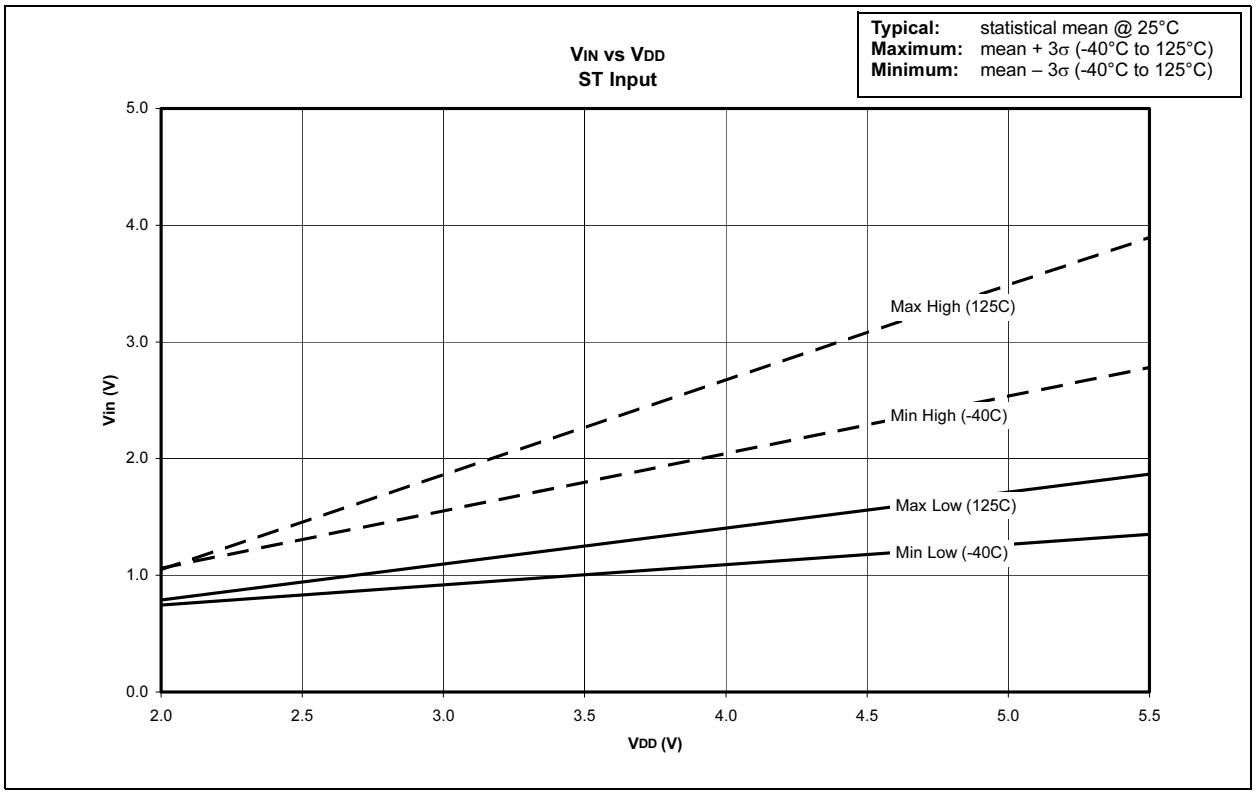


FIGURE 18-23: VIN VS VDD ST INPUT



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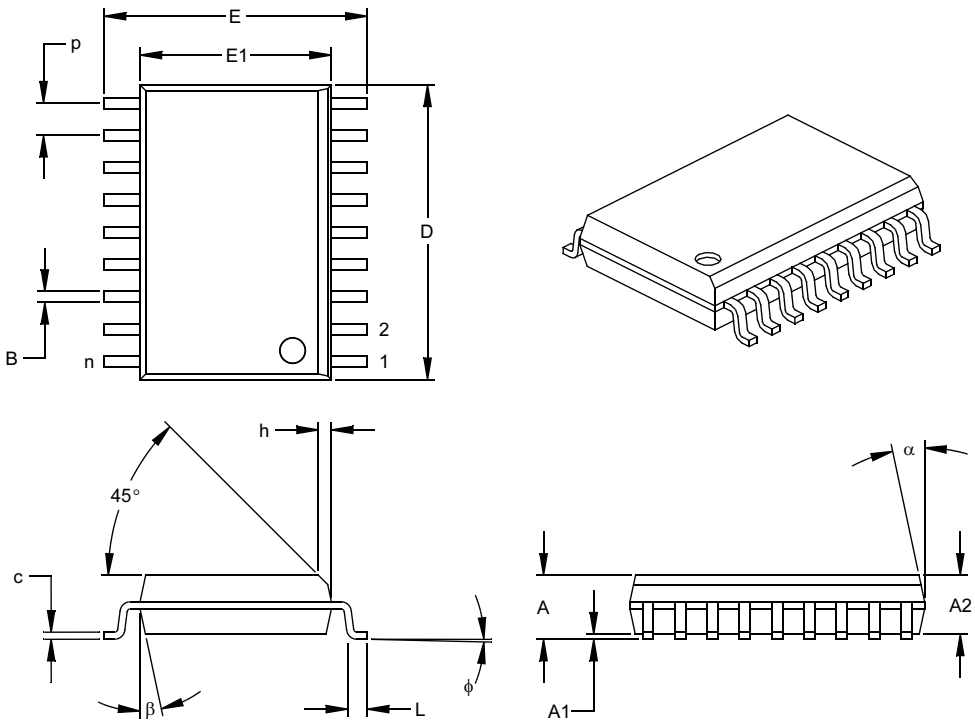
K04-051 18-Lead Plastic Small Outline (SO) – Wide, 300 mil

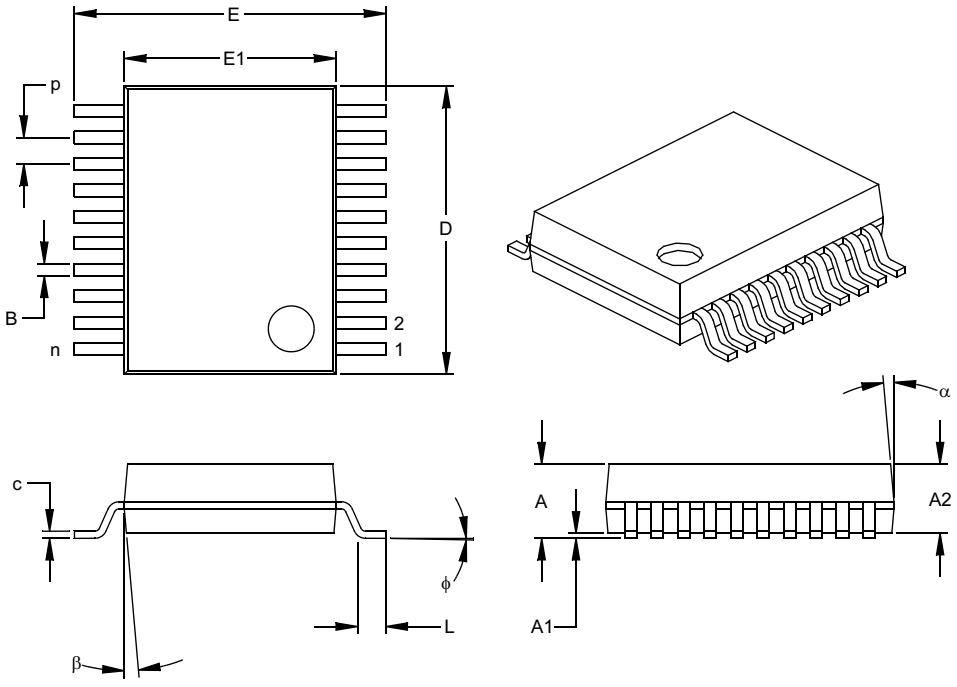


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-051

K04-072 20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	p		.026			0.65	
Overall Height	A	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	c	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ϕ	0	4	8	0.00	101.60	203.20
Lead Width	B	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-150
Drawing No. C04-072

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